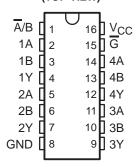
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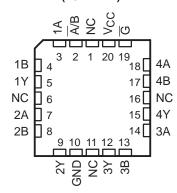
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>

SN54HC157 . . . J OR W PACKAGE SN74HC157 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t<sub>pd</sub> = 11 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

# SN54HC157 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

### description/ordering information

These data selectors/multiplexers contain inverters and drivers to supply full data selection to the four output gates. A separate strobe  $(\overline{G})$  input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'HC157 devices present true data.

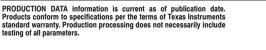
#### **ORDERING INFORMATION**

TA	PACKAGE <sup>†</sup>	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC157N	SN74HC157N
		Tube of 40	SN74HC157D	
	SOIC - D	Reel of 2500	SN74HC157DR	HC157
		Reel of 250	SN74HC157DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC157NSR	HC157
	SSOP – DB	Reel of 2000	SN74HC157DBR	HC157
		Tube of 90	SN74HC157PW	
	TSSOP - PW	Reel of 2000	SN74HC157PWR	HC157
		Reel of 250	SN74HC157PWT	
	CDIP – J	Tube of 25	SNJ54HC157J	SNJ54HC157J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC157W	SNJ54HC157W
	LCCC – FK	Tube of 55	SNJ54HC157FK	SNJ54HC157FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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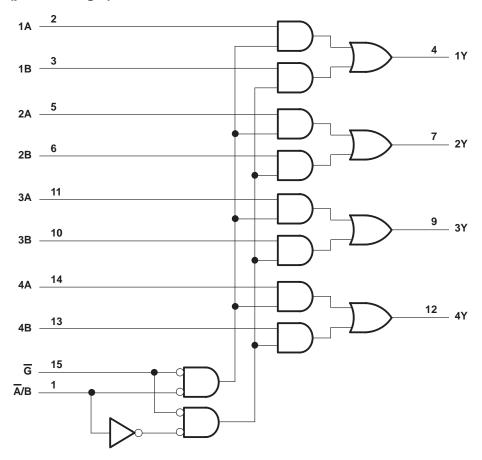


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### **FUNCTION TABLE**

G	SELECT	DA	TΑ	OUTPUT
G	A/B	Α	В	·
Н	Х	Х	Х	L
L	L	L	X	L
L	L	Н	X	Н
L	Н	Χ	L	L
L	Н	Х	Н	Н

### logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (see	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	y) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		
Continuous current through V <sub>CC</sub> or GND		±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	D package	73°C/W
•	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

		SN54HC157		SN	174HC15	57				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V <sub>CC</sub> = 2 V	1.5			1.5				
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V	
		VCC = 6 V	4.2			4.2				
		V <sub>CC</sub> = 2 V			0.5			0.5		
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V	
		V <sub>CC</sub> = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		V <sub>CC</sub> = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	$V_{CC} = 4.5 \text{ V}$		-	500		-	500	ns	
		V <sub>CC</sub> = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		NIDITIONS	.,	Т	A = 25°C	;	SN54H	C157	SN74H	IC157	
PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20  \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		IOL = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	\ \ \	T,	ղ = 25°C	;	SN54H	IC157	SN74H	IC157	LINUT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		63	125		190		160	
	A or B	Υ	4.5 V		13	25		38		32	
			6 V		11	21		32		27	
		Y	2 V		67	125		190		160	
t <sub>pd</sub>	Ā/B		4.5 V		18	25		38		31	ns
·			6 V		14	21		32		27	
			2 V		59	115		170		145	
	G	Υ	4.5 V		16	23		34		29	
			6 V		13	20		29		25	
t <sub>t</sub>			2 V		28	60		90		75	
		Υ	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

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# switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

212115	FROM	то	.,	T,	ղ = 25°C	;	SN54H	IC157	SN74H	C157	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		81	190		290		235	
	A or B	Υ	4.5 V		23	38		58		47	
			6 V		18	33		49		41	
	Ā/B		2 V		81	210		320		260	
t <sub>pd</sub>		Υ	4.5 V		23	42		64		52	ns
·			6 V		18	36		54		45	
	G		2 V		91	190		290		235	
		Y	4.5 V		24	38		58		47	
			6 V		18	33		49		41	
		Y	2 V		45	210		315		265	
t <sub>t</sub>			4.5 V		17	42		63		53	ns
			6 V		13	36		53		45	

### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	40	pF

#### PARAMETER MEASUREMENT INFORMATION **From Output VCC Test** Input 50% 50% **Under Test Point** 0 V $C_L$ - tPHL (see Note A) VOH In-Phase 90% 90% 50% Output 10% <sub>VOL</sub> **LOAD CIRCUIT** - tPHL - VCC Vон Input 90% **Out-of-Phase** 10% 10% Output VOL **VOLTAGE WAVEFORM VOLTAGE WAVEFORMS** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES **INPUT RISE AND FALL TIMES**

- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



### PACKAGE OPTION ADDENDUM





### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-86061012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8606101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54HC157J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74HC157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74HC157NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC157PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC157FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC157J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC157W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

 $<sup>^{(1)}</sup>$  The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



### PACKAGE OPTION ADDENDUM

26-Sep-2005

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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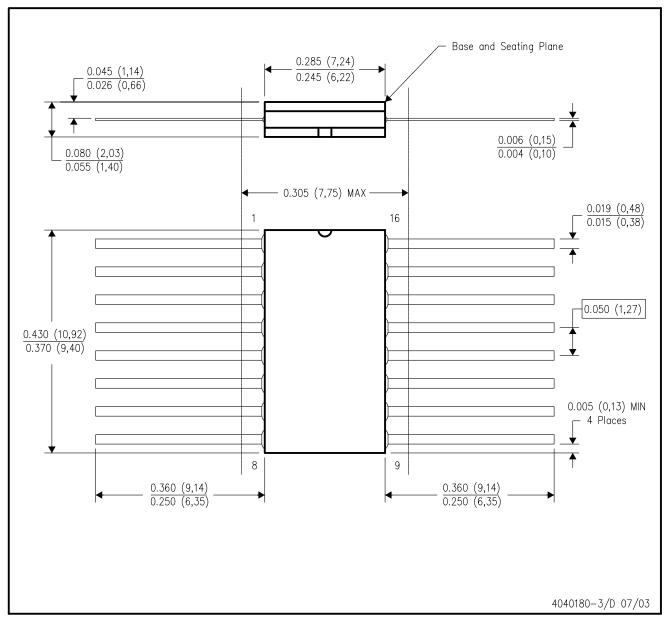
### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



### FK (S-CQCC-N\*\*)

### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

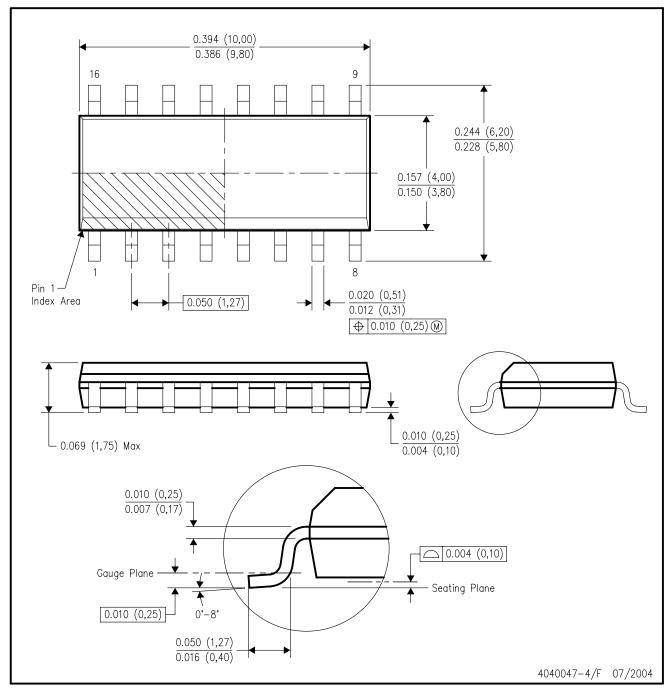


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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